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Conference Report

Two important conferences in the field of Component Technology were held during May 1979. Both of them have illustrated the growing importance of Hybrid Circuitry in particular, and Interconnection Technology in general. The first meeting was the annual Electronic Components Conference held at Cherry Hill, New Jersey, U.S. and out of a total of 67 papers given at the Conference, 40 were concerned with various aspects of Hybrid Microelectronics. Papers were concerned with substrates, materials, bonding of components to conductors etc., packaging, manufacturing technology, and reliability – all in the field of Hybrid Microelectronics. It was interesting to note the coverage given to systems to which I.C.s can be attached. This type of problem is so often ignored in the excitement of semiconductor development.

Details of the next meeting in 1980 are given in the Conference Diary section. Copies of the Proceedings of the 1979 meeting (422 pp) and previous Conferences in the series (there have been 29 to date), can be obtained from the Order Dept., IEEE, 345 East 47th St., New York, NY 10017, U.S.A.

The other conference was held in Ghent, Belgium, and was entirely devoted to Hybrid Microelectronics. 59 papers were given, in this, the second in a series now being run in Europe by the European chapters of ISHM. (See Announcements section.) The same areas of Hybrid Technology were covered, as in the case of the Cherry Hill conference, although, in this case more time was spent with papers that discussed the basic behaviour of thick and thin film devices and materials. Copies of the Proceedings of this (563 pp.) and the previous Conference in 1977, can be obtained through the office of the Chairman of the European Liaison Committee of ISHM. (See Announcements section for the address.)

Both conferences, therefore, illustrated the rapid growth over the last few years of interconnection technology as applied to microelectronics. It is a pity that a separation still occurs in engineering thinking between the different techniques used to provide interconnections to I.C.s. etc., and that conferences are not available covering all the aspects together, including printed circuit board, thick film, and thin film.

D. S. CAMPBELL

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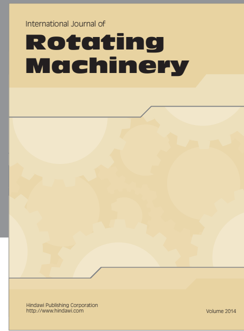
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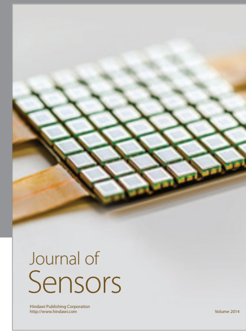
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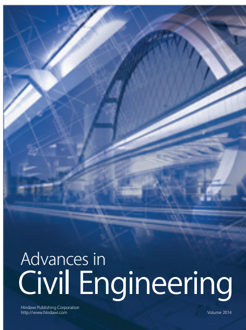
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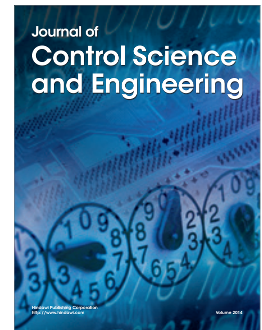
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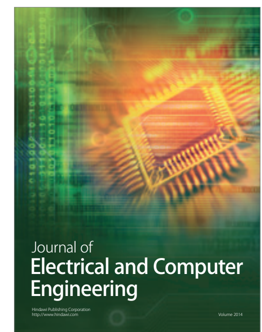
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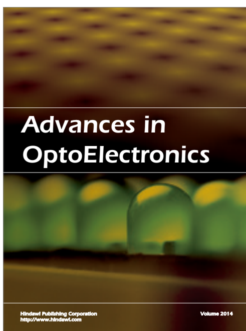
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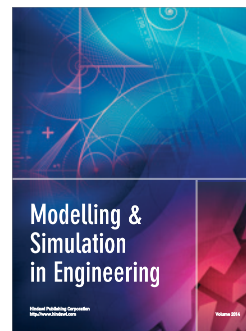
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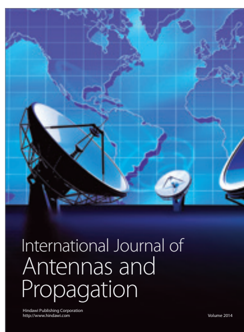
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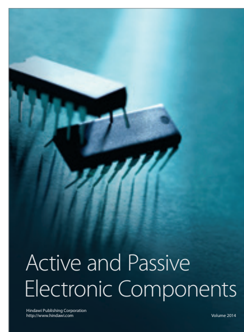
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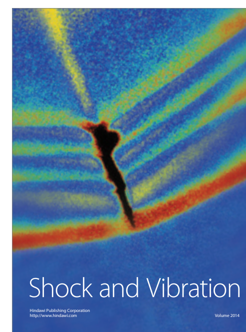
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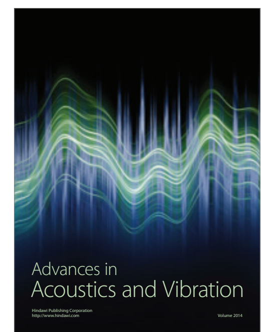
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